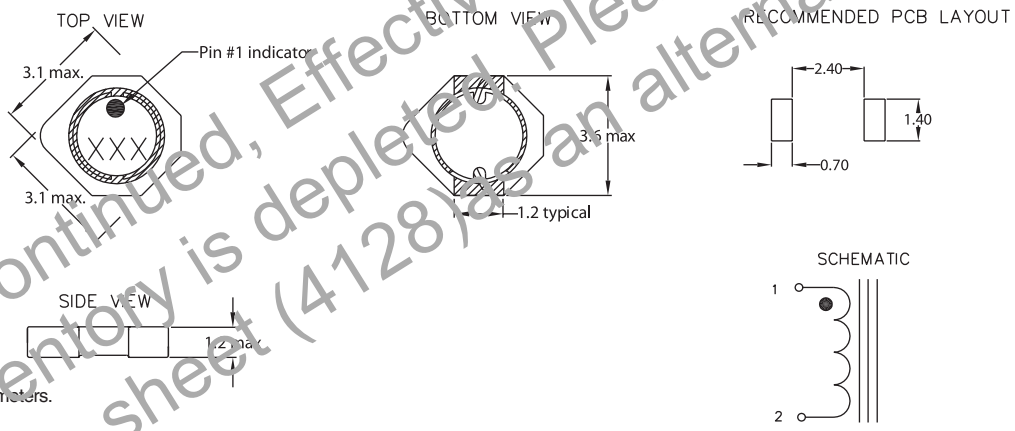
Product specifications

Part Number	Rated Inductance (µH)	OCL (1) (µH)	Part Marking Designator	Irms (2) (A)	Isat (3) (A)	DCR (Ω) typ. @ +20 °C	K-factor (4)
SD3112-1R0-R	1.0	1.11+/-30%	A	1.39	1.65	0.069	135
SD3112-1R5-R	1.5	1.70+/-30%	B	1.16	1.33	0.099	110
SD3112-2R2-R	2.2	2.41+/-30%	C	0.97	1.12	0.140	92
SD3112-3R3-R	3.3	3.24+/-30%	D	0.90	0.97	0.165	79
SD3112-4R7-R	4.7	4.72+/-30%	E	0.74	0.80	0.246	66
SD3112-6R8-R	6.8	6.47+/-30%	F	0.68	0.68	0.291	56
SD3112-8R2-R	8.2	8.50+/-30%	G	0.57	0.60	0.408	49
SD3112-100-R	10.0	10.01+/-30%	H	0.55	0.55	0.446	45
SD3112-150-R	15.0	15.28+/-20%	I	0.45	0.44	0.654	37
SD3112-220-R	22.0	21.66+/-20%	J	0.37	0.37	0.953	31
SD3112-330-R	33.0	33.30+/-20%	K	0.30	0.30	1.48	25
SD3112-470-R	47.0	47.44+/-20%	L	0.270	0.25	1.85	21
SD3112-680-R	68.0	68.10+/-20%	M	0.228	0.211	2.56	17
SD3112-820-R	82.0	83.19+/-20%	N	0.213	0.190	2.93	16
SD3112-101-R	100.0	99.8+/-20%	O	0.184	0.174	3.95	14
SD3112-151-R	150.0	149.4+/-20%	P	0.149	0.142	6.01	12
SD3112-221-R	220.0	219.9+/-20%	Q	0.121	0.117	9.12	10

(1) Open Circuit Inductance Test Parameters: 100 kHz, 0.1 V, 0.0 Adc.
(2) Irms: DC current for an approximate DT of 40 °C without core loss. Derating is necessary for AC currents. PCB layout, trace thickness and width, air-flow, and proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed +125 °C under worst case operating conditions verified in the end application.
(3) Isat Amperes peak for approximately 30% rolloff @ 20 °C)
(4) K-factor: Used to determine B p-p for core loss (see graph).
B p-p = K*L^.41*ΔI^.61 (mT), K: (K factor from table), L: (Inductance in µH), ΔI(Peak to peak ripple current in Amps)

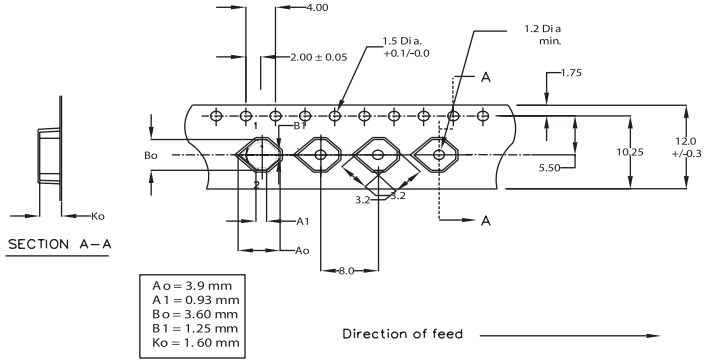
Dimensions- mm



Dimensions are in millimeters.

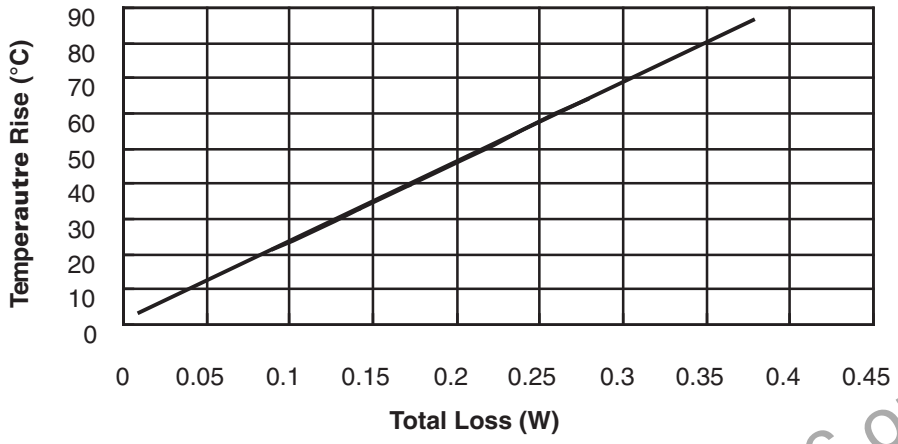
Part Marking:
3 Digit Marking: (1st digit: Indicates inductance value per letter in Part Marking Designator); (2nd digit: Bi-weekly production date code); (3rd digit: Last digit of the year produced).
Do not route traces or vias underneath the inductor

Packaging information- mm

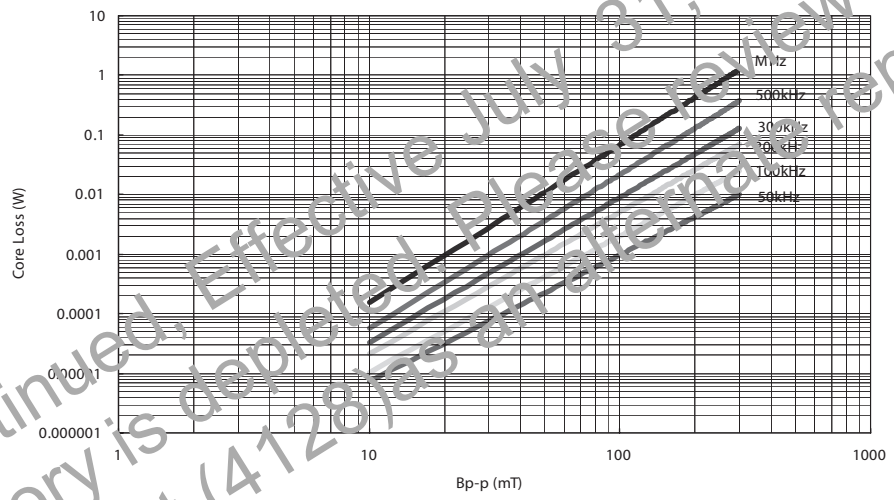


Parts packaged on 13" Diameter reel, 4,100 parts per reel.

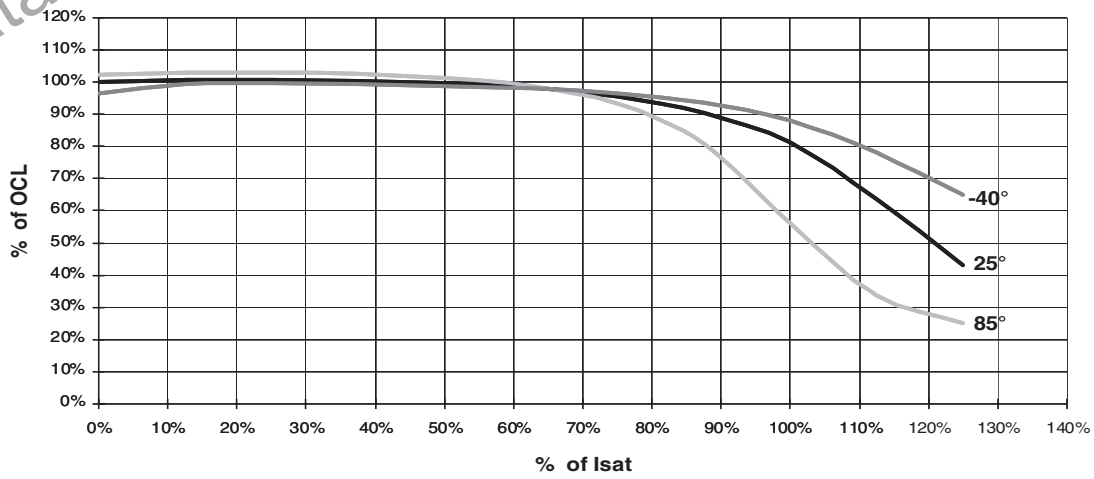
Temperature rise vs total loss loss



Core loss vs Bp-p



Inductance characteristics



Solder Reflow Profile

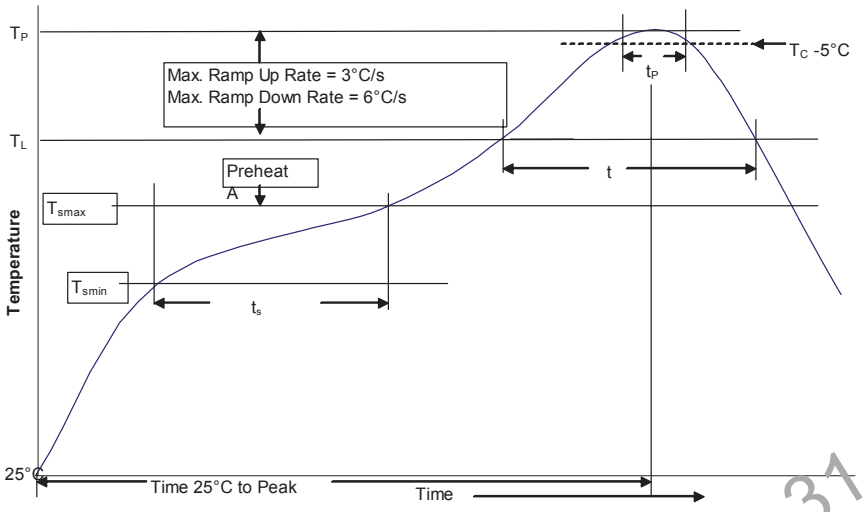


Table 1 - Standard SnPb Solder (T_C)

Package Thickness	Volume mm³ <350	Volume mm³ ≥350
<2.5mm	235°C	220°C
≥2.5mm	220°C	220°C

Table 2 - Lead (Pb) Free Solder (T_C)

Package Thickness	Volume mm³ <350	Volume mm³ 350 - 2000	Volume mm³ >2000
<1.6mm	260°C	260°C	260°C
1.6 – 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

Reference JDEC J-STD-020

Profile Feature		Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak	• Temperature min. (T_{smin})	100°C	150°C
	• Temperature max. (T_{smax})	150°C	200°C
	• Time (T_{smin} to T_{smax}) (t_s)	60-120 Seconds	60-120 Seconds
Average ramp up rate T_{smax} to T_p		3°C/ Second Max.	3°C/ Second Max.
Liquidous temperature (T_L) Time at liquidous (t_L)		183°C 60-150 Seconds	217°C 60-150 Seconds
Peak package body temperature (T_P)*		Table 1	Table 2
Time (t_p)** within 5°C of the specified classification temperature (T_C)		20 Seconds**	30 Seconds**
Average ramp-down rate (T_p to T_{smax})		6°C/ Second Max.	6°C/ Second Max.
Time 25°C to Peak Temperature		6 Minutes Max.	8 Minutes Max.

* Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.

** Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.

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